



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-03-02
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		


Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD3N80K5	TQDP*VJ8AB5V	A	Z4XA	2015-03-02
Amount		UoM	Unit type	ST ECOPACK Grade
330.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	6.5 - 6.1 - 2.3	3	gull wing	
Comment	Package: TO 252 DPAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TQDP*VJ8B5V					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.457	mg	supplier	die	Silicon (Si)	7440-21-3		3.031	mg	876772	9185
				supplier	metallization	Aluminium (Al)	7429-90-5		0.348	mg	100665	1055
				supplier	Passivation	Silicon Nitride	12033-89-5		0.019	mg	5496	58
				supplier	Passivation	Silicon Oxide	7631-86-9		0.030	mg	8678	91
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	289	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.021	mg	6075	64
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.007	mg	2025	21
Leadframe	Copper & its alloys	153.963	mg	supplier	Alloy	Copper(Cu)	7440-50-8		153.685	mg	998194	465712
				supplier	Alloy	Phosphorus(P)	12185-10-3		0.047	mg	305	142
				supplier	Alloy	Iron(Fe)	7439-89-6		0.231	mg	1500	700
Die attach	Other Organic Materials	11.405	mg	supplier	Soft solder	Silver(Ag)	7440-22-4		0.352	mg	30864	1067
				JIG R	Soft solder	Lead(Pb)	7439-92-1	7a-Lead in high me	10.823	mg	948970	32797
Bonding wire	Other inorganic materials	0.371	mg	supplier	Soft solder	Tin(Sn)	7440-31-5		0.230	mg	20167	697
				supplier	Bonding wire	Aluminium (Al)	7429-90-5		0.371	mg	1000000	1124
				supplier	Mold compound	Silicone dioxide	60676-86-0		138.909	mg	870008	420936
				supplier	Mold compound	Polymer(phenyl glycidyl ether) -co-dicyclopent	119345-05-0		7.983	mg	49999	24191
Encapsulation	Other Organic Materials	159.664	mg	supplier	Mold compound	Diglycidylether of Tetramethyl biphenol	85954-11-6		7.983	mg	49999	24191
				supplier	Mold compound	Phenol, Polymer with 1,4-bis(methoxymethyl)	26834-02-6		3.193	mg	19998	9676
				supplier	Mold compound	Carbon black	1333-86-4		1.596	mg	9996	4836
Finishing	Other inorganic materials	1.140	mg	supplier	Connection coating	Tin(Sn)	7440-31-5		1.140	mg	1000000	3455